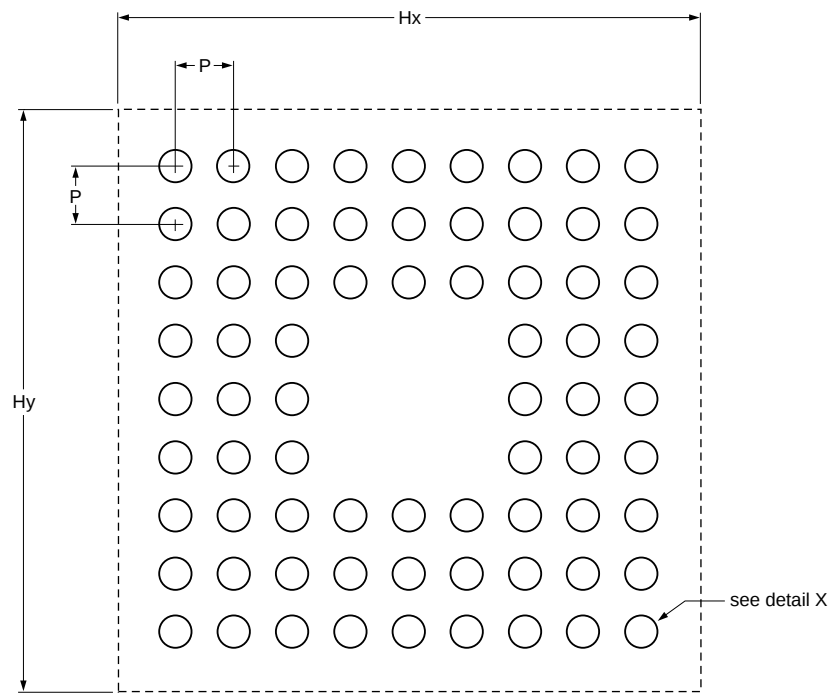


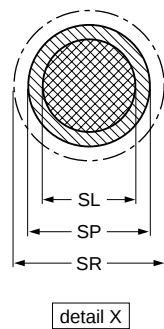
Footprint information for reflow soldering of VFPGA48 package

SOT1063-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
-  occupied area
-  solder resist



| DIMENSIONS in mm |       |       |       |       |       |
|------------------|-------|-------|-------|-------|-------|
| P                | SL    | SP    | SR    | Hx    | Hy    |
| 0.40             | 0.250 | 0.275 | 0.350 | 4.400 | 4.400 |